

# LNJ412K82RA1

## Ultra High Bright Surface Mounting Chip LED

InGaAlP TSS Type

■ Absolute Maximum Ratings  $T_a = 25^\circ\text{C}$

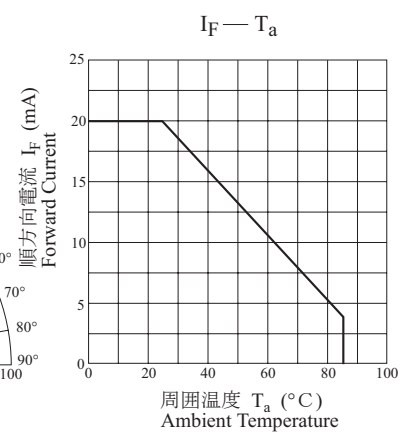
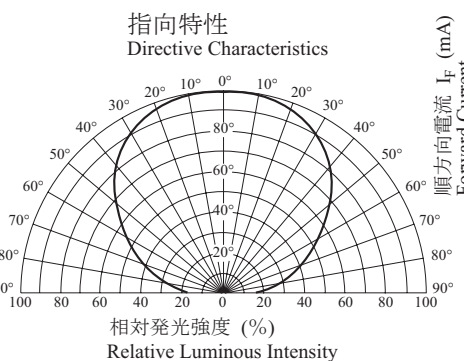
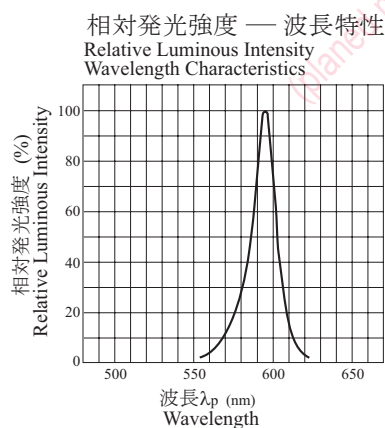
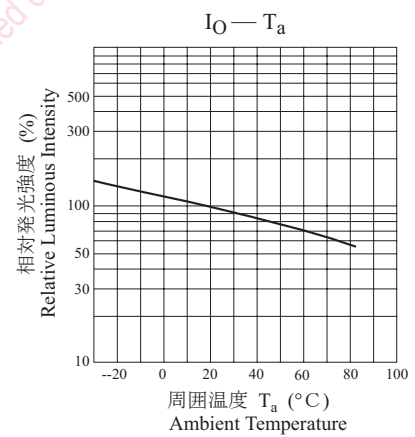
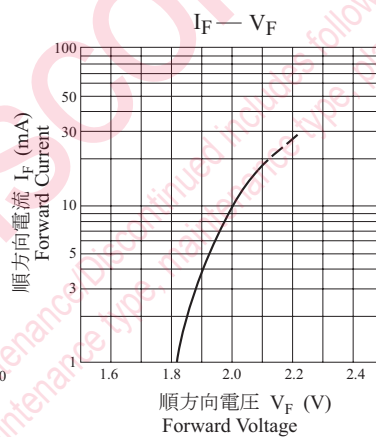
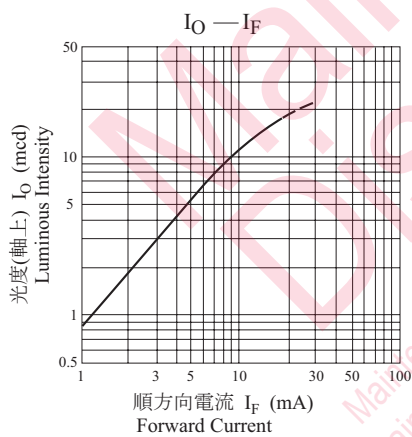
Parameter	Symbol	Rating	Unit
Power dissipation	$P_D$	55	mW
Forward current	$I_F$	20	mA
Pulse forward current	$I_{FP}$	60	mA
Reverse voltage	$V_R$	4	V
Operating ambient temperature	$T_{opr}$	-30 to +85	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-40 to +100	$^\circ\text{C}$

■ Lighting Color / Lens Color

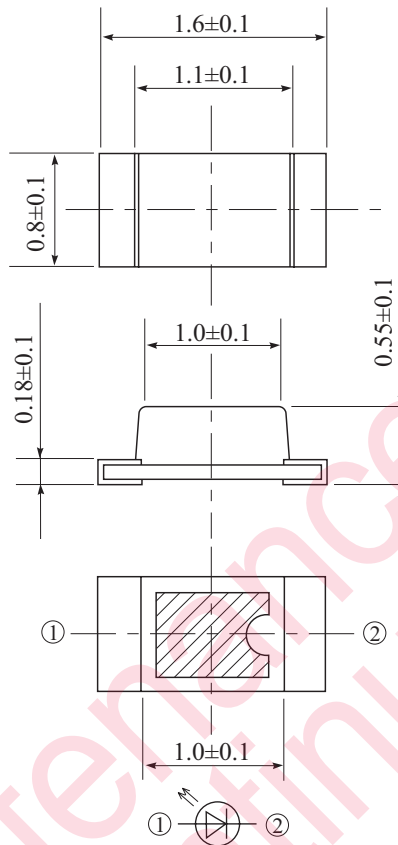
- Amber / Clear

■ Electro-Optical Characteristics  $T_a = 25^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	$I_O$		6.1	11.0	31.0	mcd
Forward current	$I_F$			10		mA
Forward voltage	$V_F$	$I_F = 10\text{ mA}$		2.0	2.3	V
Peak emission wavelength	$\lambda_P$	$I_F = 10\text{ mA}$		595		nm
Spectral half band width	$\Delta\lambda$	$I_F = 10\text{ mA}$		15		nm
Reverse current	$I_R$	$V_R = 4\text{ V}$			100	$\mu\text{A}$



■ Package (Unit: mm)



- Pin name
- 1: Anode
- 2: Cathode

Maintenance/Discontinued

Maintenance/Discontinued includes following four Product lifecycle stage.  
(planned maintenance type, maintenance type, planned discontinued type, discontinued type)

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